

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

<b>Title of Invention</b>	Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking
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Application Number : 10/050507



Confirmation Number: 7687

First Named Applicant: Teck Lee

Attorney Docket Number: MTI-31607

Art Unit: 2813

Examiner: Jack SJ Chen

Search string: ( 6624060 or 20020027080 or 20030134450 ).pn

## US Patent Documents

**Note: Applicant is not required to submit a paper copy of cited US Patent Documents**

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6624060	2003-09-23	Chen et al.		438	613

## US Published Applications

**Note: Applicant is not required to submit a paper copy of cited US Published Applications**

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020027080	2002-03-07	Yoshioka et al.	A1	205	123
	2	20030134450	2003-07-17	Lee	A1	438	106

## Signature

Examiner Name	Date